Chemical content 74AUP2G125GN

nexperia

Type number	Package	Package description	Total product weight
74AUP2G125GN	SOT1116	X2SON8	1.16443 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935288988115	6	1	260	30 s	1	240	20 s	3	Seremban, Malaysia; Ayutthaya, Thailand; Nijmegen, Netherlands; Suzhou, China; Bangkok, Thailand	Pb D

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.05068	100.00000	4.35213
		subTotal		0.05068	100.00000	4.35213
Component	Additive	Non hazardous	Proprietary	0.00100	5.00000	0.08588
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00100	5.00000	0.08588
		Silica -amorphous-	7631-86-9	0.01000	50.00000	0.85879
	Polymer	Epoxy resin system	Proprietary	0.00600	30.00000	0.51527
		Phenol Formaldehyde resin (generic)	9003-35-4	0.00200	10.00000	0.17176
		subTotal		0.02000	100.00000	1.71758
Lead Frame	Copper alloy	Chromium (Cr)	7440-47-3	0.00122	0.24000	0.10512
		Copper (Cu)	7440-50-8	0.48159	94.43000	41.35869
		Tin (Sn)	7440-31-5	0.00122	0.24000	0.10512
		Zinc (Zn)	7440-66-6	0.00107	0.21000	0.09198
	Pure metal layer	Gold (Au)	7440-57-5	0.00026	0.05000	0.02190
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.02366	4.64000	2.03224
		Palladium (Pd)	7440-05-3	0.00097	0.19000	0.08322
		subTotal		0.51000	100.00000	43.79827
Mould Compound	Filler	Silica -amorphous-	7631-86-9	0.10600	20.00000	9.10317
		Silica fused	60676-86-0	0.34185	64.50000	29.35771
	Flame retardant	Metal hydroxide	Proprietary	0.01590	3.00000	1.36547
	Impurity	Silicon Dioxide (SiO2)	14808-60-7	0.00265	0.50000	0.22758
	Pigment	Carbon black	1333-86-4	0.00159	0.30000	0.13655
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	0.01166	2.20000	1.00135
		Phenolic resin	Proprietary	0.01325	2.50000	1.13790
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.03710	7.00000	3.18611
		subTotal		0.53000	100.00000	45.51584
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00000	0.00300	0.00008
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00003
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00003
		Lead (Pb)	7439-92-1	0.00000	0.00500	0.00013
	Tin solder	Tin (Sn)	7440-31-5	0.03000	99.99000	2.57611
		subTotal		0.03000	100.00000	2.57638
Wire	Gold alloy	Gold (Au)	7440-57-5	0.02352	99.00000	2.01965

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
		Palladium (Pd)	7440-05-3	0.00024	1.00000	0.02040
		subTotal		0.02376	100.00000	2.04005

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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